## Best Known Method: Contact Hole / Pillar Measurement Data Collection

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|  | Averaging is your friend when measuring LCDU, LEPE, defectivity, and other hole/pillar measurements. You want <br> $>200$ features per SEM image ( $>400$ preferred), and at least 20 SEM images to average together. The images being <br> averaged together should be nominally the same (same pattern type and size and the same process conditions). <br> The required number of features to use depends on the desired size of the error bars on your results. The error <br> bars will get smaller as you average together more features. For defectivity measurements, more images lower the <br> defectivity measurement floor (the smallest defectivity rate that can be detected). |
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| Image Size | At least $1024 \times 1024$ (or similar) is preferred; $2048 \times 2048$ is better. |
| Pixel size | Square pixels should be used. For circular features, the pixel size should be about CD/30 or less. For slot contacts, <br> the pixel size should be about CD/30 when using the CD of the smaller dimension. |
| Image file type | Uncompressed images such as TIFF |
| Filtering/smoothing | For best results the images should not be filtered or smoothed. Filtering will change the measured LCDU and LEPE, <br> among other metrics. |
| Condition files | For automated across-field, across-wafer, and other data analysis, the SEM condition files need to be available with <br> the SEM images (for example, the Hitachi CND folder or AMAT .xml files). |

